

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	50	V
Collector to Emitter Voltage	V_{CEO}	50	V
Emitter to Base Voltage	V_{EBO}	5	V
Collector Current - Continuous	I_C	3	A
Collector Base - Continuous	I_B	0.5	A
Peak Collector Current	I_{CM}	5	A
Total Power Dissipation	$P_{tot} \text{ } ^{1,4}$	550	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-65 150	

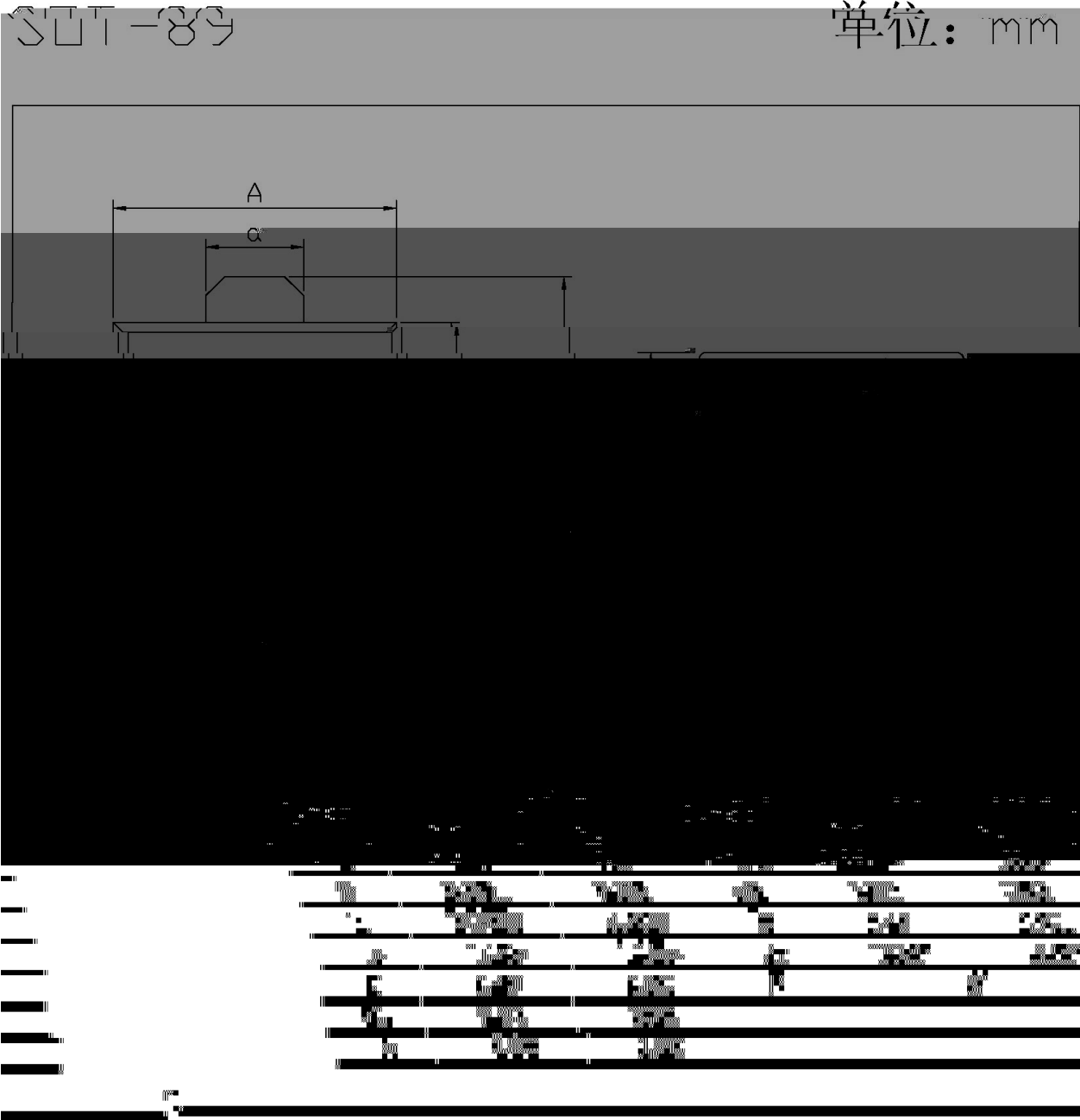
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Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector Cut-Off Current	I_{CBO}	$V_{CB}=50V \quad I_E=0$			100	nA
Collector Cut-Off Current	I_{CBO}	$V_{CB}=50V \quad I_E=0 \quad T_j=150$			50	A
Collector Cut-Off Current	I_{CES}	$V_{CE}=50V \quad V_{BE}=0$			100	nA
Emitter Base Cut-Off Current	I_{EBO}	$V_{EB}=5.0V \quad I_C=0$			100	nA
DC Current Gain	$h_{FE(1)}$	$V_{CE}^{CE}=2.0V \quad I_C=0.1A$	300			
	$h_{FE(2)}$	$V_{CE}=2.0V \quad I_C=0.5A$	300			
	$h_{FE(3)*}$	$V_{CE}=2.0V \quad I_C \neq 1.0A$	300		700	

/ Electrical Characteristic Curve



/ Package Dimensions




() / Temperature Profile for IR Reflow Soldering(Pb-Free)

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1 ǀ ڤ □ ȳ 150 ǀ 180 † ǀ ʼH ڤ 60 ǀ 90sec;

2 Š Œ □ ȳ 245 ° 5 † ǀ ʼH ڤ ʼY ʼ ڤ 5 ° 0.5sec;

3 ǀ ʼ ڤ ڤ ڤ ȳ ڤ 2 ǀ 10 † /sec.

Note:

1.Preheating:150~180 † , Time:60~90sec.

2.Peak Temp.:245 ° 5 † , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 † /sec.

/ Resistance to Soldering Heat Test Conditions

□ ȳ χ 260 ° 5 †

ʼH ڤ χ 10 ° 1 sec.

Temp.:260±5

Time:10±1 sec

/ Packaging SPEC.

ڤ ڤ ڤ / REEL

Package Type	Units	Dimension	(unit mm ³)
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